

BOARD CHARACTERISTICS

Copper Layer Count: 4

Board overall dimensions: 36.00 mm x 16.00 mm

Min track/spacing: 9 mils / 7 mils

Copper Finish: Immersion gold

Castellated pads: No

Edge card connectors: No

Board Thickness: 1.6000 mm

Min hole diameter: 0.3000 mm

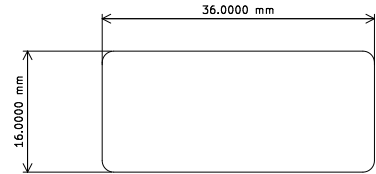
Impedance Control: Yes

Plated Board Edge: No

REVISION HISTORY				
ZONE	REV	DESCRIPTION	DATE	APPROVED

Impedance control required:

1. For F.Cu layer, 9 mils trace / 7 mils space = 100 Ohms Differential,  $\pm 10\%$ , ref to In1.Cu.
2. For B.Cu layer, 9 mils trace / 7 mils space = 100 Ohms single end,  $\pm 10\%$ , ref to In2.Cu.



STACKUP TABLE:

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.2032 mm	Not specified	4.5	0.02
In1.Cu	copper		0.035 mm		1	0
Dielectric 2	core	FR4	1.0336 mm	Not specified	4.5	0.02
In2.Cu	copper		0.035 mm		1	0
Dielectric 3	prepreg	FR4	0.2032 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0



File:	
P/N: BTS22314316A	
Title: RJ45_Module	
Size: A4	Date: 2023-07-26
Rev: 1.0	
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